

# Quad 2-Input AND Gate

## MC74VHC08, MC74VHCT08A

The MC74VHC08 and MC74VHCT08A are high speed CMOS quad 2-input AND gate fabricated with silicon gate CMOS technology. These achieve high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The MC74VHC08 inputs are compatible with standard CMOS levels while the MC74VHCT08A inputs are compatible with TTL levels. This device can be used as a level converter for interfacing 3.3 V to 5.0 V, because it has full 5.0 V CMOS level output swings.

The MC74VHC08 and MC74VHCT08A internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output. The input structures tolerate voltages up to 5.5 V, allowing the interface of 5 V systems to 3 V systems.

The MC74VHCT08A output structures provide protection when  $V_{CC} = 0$  V. These output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

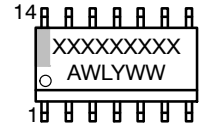
### Features

- High Speed:  $t_{PD} = 4.3$  ns (Typ) at  $V_{CC} = 5.0$  V
- Low Power Dissipation:  $I_{CC} = 2.0$   $\mu$ A (Max) at  $T_A = 25^\circ$ C
- High Noise Immunity:  $V_{NIH} = V_{NIL} = 28\%$
- Power Down Protection Provided
- Balanced Propagation Delays
- Designed for 2.0 V to 5.5 V Operating Range
- Low Noise:  $V_{OLP} = 0.8$  V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 100 mA
- ESD Performance: Human Body Model > 2000 V
- Chip Complexity: 24 FETs or 6 Equivalent Gates
- -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

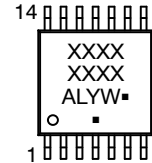
### MARKING DIAGRAMS



SO-14  
D SUFFIX  
CASE 751A



TSSOP-14  
DT SUFFIX  
CASE 948G



XXXX = Specific Device Code  
 A = Assembly Location  
 WL, L = Wafer Lot  
 Y = Year  
 WW, W = Work Week  
 G or ■ = Pb-Free Device

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.

# MC74VHC08, MC74VHCT08A

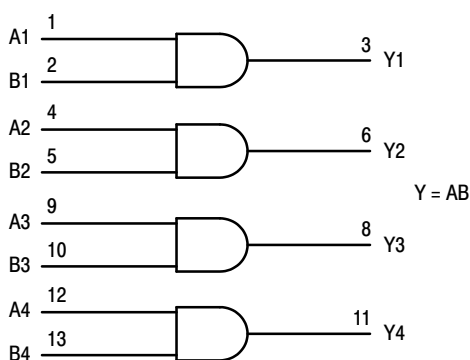


Figure 1. Logic Diagram

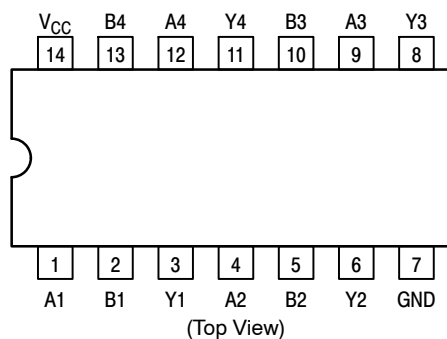


Figure 2. Pinout

## FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
$V_{CC}$	DC Supply Voltage	-0.5 to +6.5	V	
$V_{IN}$	DC Input Voltage	-0.5 to +6.5	V	
$V_{OUT}$	DC Output Voltage (MC74VHC)	-0.5 to $V_{CC} + 0.5$	V	
	DC Output Voltage (MC74VHCT)	Active Mode (High or Low State) Tristate Mode (Note 1) Power-Off Mode ( $V_{CC} = 0$ V)		-0.5 to $V_{CC} + 0.5$ -0.5 to +6.5 -0.5 to +6.5
$I_{IN}$	DC Input Current, per Pin	±20	mA	
$I_{OUT}$	DC Output Current, per Pin	±25	mA	
$I_{CC}$	DC Supply Current, $V_{CC}$ and GND Pins	±50	mA	
$I_{IK}$	Input Clamp Current	-20	mA	
$I_{OK}$	Output Clamp Current	MC74VHC	±20	mA
		MC74VHCT	-20	
$T_{STG}$	Storage Temperature Range	-65 to +150	°C	
$T_L$	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C	
$T_J$	Junction Temperature Under Bias	±150	°C	
$\theta_{JA}$	Thermal Resistance (Note 2)	SOIC-14	116	°C/W
		TSSOP-14	150	
$P_D$	Power Dissipation in Still Air at 25°C	SOIC-14	1077	mW
		TSSOP-14	833	
MSL	Moisture Sensitivity	Level 1	-	
$F_R$	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
$V_{ESD}$	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	> 2000 N/A	V
$I_{LATCHUP}$	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.
2. Measured with minimum pad spacing on an FR4 board, using 76mm-by-114mm, 2-ounce copper trace no air flow per JESD51-7.
3. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.
4. Tested to EIA/JESD78 Class II.

## MC74VHC08, MC74VHCT08A

### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
<b>MC74VHC</b>				
$V_{CC}$	DC Supply Voltage	2.0	5.5	V
$V_{IN}$	DC Input Voltage (Note 5)	0	5.5	V
$V_{OUT}$	DC Output Voltage (Note 5)	0	$V_{CC}$	V
$T_A$	Operating Temperature Range	-55	+125	°C
$t_r, t_f$	Input Rise or Fall Time	$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ 0 $V_{CC} = 4.5\text{ V to }5.5\text{ V}$ 0	100 20	ns/V
<b>MC74VHCT</b>				
$V_{CC}$	DC Supply Voltage	2.0	5.5	V
$V_{IN}$	DC Input Voltage (Note 5)	0	5.5	V
$V_{OUT}$	DC Output Voltage (Note 5)	Active Mode (High or Low State) 0 Tristate Mode 0 Power-Off Mode ( $V_{CC} = 0\text{ V}$ ) 0	$V_{CC}$ 5.5 5.5	V
$T_A$	Operating Temperature Range	-55	+125	°C
$t_r, t_f$	Input Rise or Fall Time	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

# MC74VHC08, MC74VHCT08A

## DC ELECTRICAL CHARACTERISTICS (MC74VHC08)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	T <sub>A</sub> = 25°C			T <sub>A</sub> = ≤ 85°C		T <sub>A</sub> = ≤ +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V <sub>IH</sub>	High-Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 4.2			1.5 2.1 3.15 4.2		1.5 2.1 3.15 4.2	V	
V <sub>IL</sub>	Low-Level Input Voltage		2.0 3.0 4.5 5.5			0.5 0.9 1.35 1.8		0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V	
V <sub>OH</sub>	High-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>								V	
		I <sub>OH</sub> = -50 μA	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		
		I <sub>OH</sub> = -4 mA I <sub>OH</sub> = -8 mA	3.0 4.5	2.58 3.94			2.48 3.80		2.40 3.70		
V <sub>OL</sub>	Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>								V	
		I <sub>OL</sub> = 50 μA	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1	0.1 0.1 0.1		
		I <sub>OL</sub> = 4 mA I <sub>OL</sub> = 8 mA	3.0 4.5			0.36 0.36	0.44 0.44		0.55 0.55		
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	0 to 5.5			±0.1		±1.0		μA	
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5			2.0		20	40	μA	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## AC ELECTRICAL CHARACTERISTICS (MC74VHC08)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			T <sub>A</sub> = ≤ 85°C		T <sub>A</sub> = ≤ +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay, A or B to $\bar{Y}$	C <sub>L</sub> = 15 pF C <sub>L</sub> = 50 pF	3.0 - 3.6		6.2 8.7	8.8 12.3	1.0 1.0	10.5 14.0	1.0 1.0	10.5 14.0	ns
		C <sub>L</sub> = 15 pF C <sub>L</sub> = 50 pF	4.5 - 5.5		4.3 5.8	5.9 7.9	1.0 1.0	7.0 9.0	1.0 1.0	7.0 9.0	
C <sub>in</sub>	Input Capacitance				4.0	10		10		10	pF

C <sub>PD</sub>	Power Dissipation Capacitance (Note 6)	5.0	Typical @ 25°C				pF
			18				

6. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>/4 (per gate). C<sub>PD</sub> is used to determine the no-load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

## NOISE CHARACTERISTICS

Symbol	Characteristic	Test Conditions	T <sub>A</sub> = 25°C		Unit
			Typ	Max	
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	V <sub>CC</sub> = 5.0 V t <sub>R</sub> = t <sub>F</sub> = 3.0 ns C <sub>L</sub> = 50 pF	0.3	0.8	V
V <sub>OLV</sub>	Quiet Output Minimum Dynamic V <sub>OL</sub>		-0.3	-0.8	V
V <sub>IHD</sub>	Minimum High Level Dynamic Input Voltage			3.5	V
V <sub>ILD</sub>	Maximum Low Level Dynamic Input Voltage			1.5	V

# MC74VHC08, MC74VHCT08A

## DC ELECTRICAL CHARACTERISTICS (MC74VHCT08A)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	T <sub>A</sub> = 25°C			T <sub>A</sub> = ≤ 85°C		T <sub>A</sub> = ≤ +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V <sub>IH</sub>	High-Level Input Voltage		3.0 4.5 5.5	1.2 2.0 2.0			1.2 2.0 2.0		1.2 2.0 2.0		V
V <sub>IL</sub>	Low-Level Input Voltage		3.0 4.5 6.0			0.53 0.8 0.8		0.53 0.8 0.8		0.53 0.8 0.8	V
V <sub>OH</sub>	High-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>									V
		I <sub>OH</sub> = -50 μA	3.0 4.5	2.9 4.4	3.0 4.5		2.9 4.4		2.9 4.4		
		I <sub>OH</sub> = -4 mA I <sub>OH</sub> = -8 mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V <sub>OL</sub>	Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>									V
		I <sub>OL</sub> = 50 μA	3.0 4.5		0.0 0.0	0.1 0.1		0.1 0.1		0.1 0.1	
		I <sub>OL</sub> = 4 mA I <sub>OL</sub> = 8 mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μA
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5			2.0		20		40	μA
I <sub>CC(T)</sub>	Additional Quiescent Supply Current	V <sub>IN</sub> = 3.4 V, any one input; V <sub>IN</sub> = V <sub>CC</sub> or GND, other inputs	5.5			1.35		1.5		1.65	mA
I <sub>OPD</sub>	Output Leakage Current	V <sub>OUT</sub> = 5.5 V	0.0			0.5		5.0		10	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

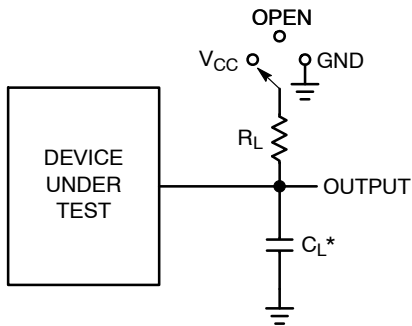
## AC ELECTRICAL CHARACTERISTICS (MC74VHCT08A)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			T <sub>A</sub> = ≤ 85°C		T <sub>A</sub> = ≤ +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay, A or B to $\bar{Y}$	C <sub>L</sub> = 15 pF C <sub>L</sub> = 50 pF	3.0 - 3.6		6.2 8.7	8.8 12.3		10.5 14.0		14.0 17.5	ns
		C <sub>L</sub> = 15 pF C <sub>L</sub> = 50 pF	4.5 - 5.5		4.3 5.8	5.9 7.9		7.0 9.0		9.0 11.0	
C <sub>in</sub>	Input Capacitance				4.0	10		10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 6)			5.0	Typical @ 25°C						
					20					pF	

## NOISE CHARACTERISTICS

Symbol	Characteristic	Test Conditions	T <sub>A</sub> = 25°C		Unit
			Typ	Max	
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	V <sub>CC</sub> = 5.0 V t <sub>R</sub> = t <sub>F</sub> = 3.0 ns C <sub>L</sub> = 50 pF	0.4	0.8	V
V <sub>OLV</sub>	Quiet Output Minimum Dynamic V <sub>OL</sub>		-0.4	-0.8	V
V <sub>IHD</sub>	Minimum High Level Dynamic Input Voltage			2.0	V
V <sub>ILD</sub>	Maximum Low Level Dynamic Input Voltage			0.8	V

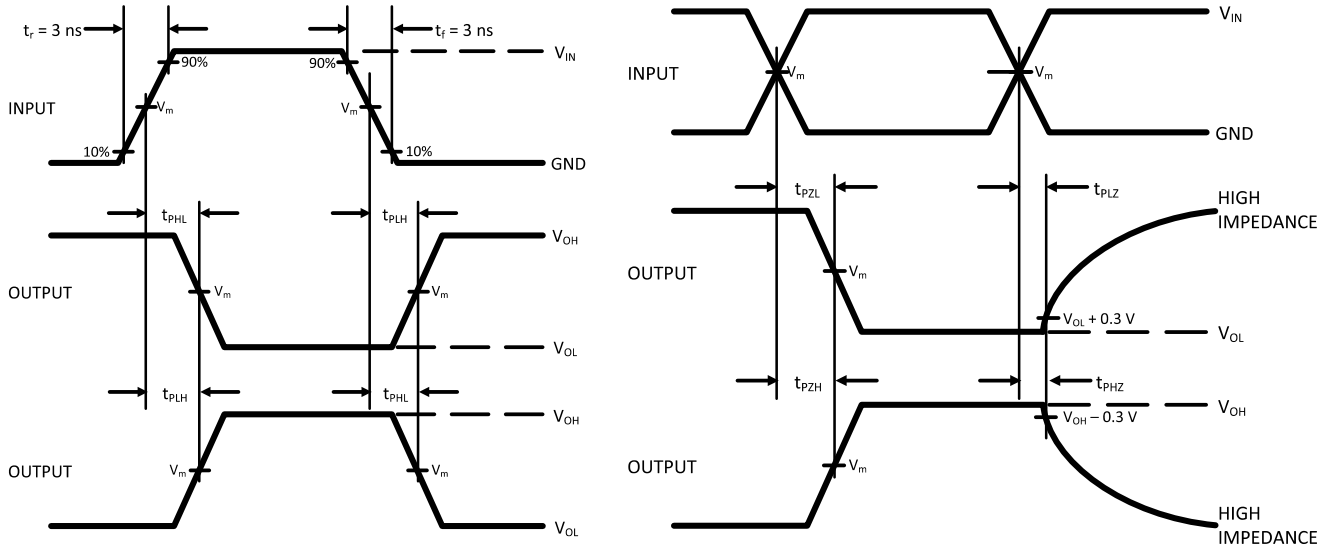
# MC74VHC08, MC74VHCT08A



\*C<sub>L</sub> Includes probe and jig capacitance

Test	Switch Position	C <sub>L</sub>	R <sub>L</sub>
t <sub>PLH</sub> / t <sub>PHL</sub>	Open	See AC Characteristics table	1 kΩ
t <sub>PLZ</sub> / t <sub>PZL</sub>	V <sub>CC</sub>		
t <sub>PHZ</sub> / t <sub>PZH</sub>	GND		

Figure 1. Test Circuit



Device	V <sub>IN</sub> , V	V <sub>m</sub> , V
MC74VHC08	V <sub>CC</sub>	50% x V <sub>CC</sub>
MC74VHCT08A	3 V	1.5 V

Figure 2. Switching Waveforms

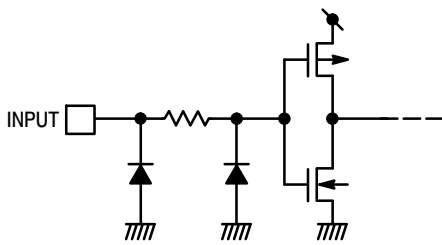


Figure 3. Input Equivalent Circuit (MC74VHC08, MC74VHCT08A)

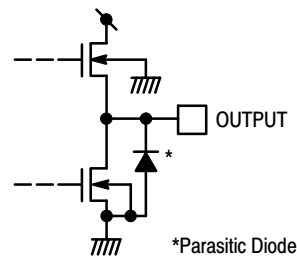


Figure 4. Output Equivalent Circuit (MC74VHCT08A)

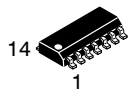
## MC74VHC08, MC74VHCT08A

### ORDERING INFORMATION

Device	Markinig	Package	Shipping <sup>†</sup>
MC74VHC08DR2G	VHC08G	SOIC-14	2500 Units / Tape & Reel
MC74VHC08DTR2G	VHC 08	TSSOP-14	2500 Units / Tape & Reel
MC74VHC08DTR2G-Q*	VHC 08	TSSOP-14	2500 Units / Tape & Reel
MC74VHCT08ADR2G	VHCT08G	SOIC-14	2500 Units / Tape & Reel
MC74VHCT08ADTR2G	VHCT 08A	TSSOP-14	2500 Units / Tape & Reel
MC74VHCT08ADTR2G-Q*	VHCT 08A	TSSOP-14	2500 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

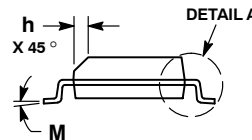
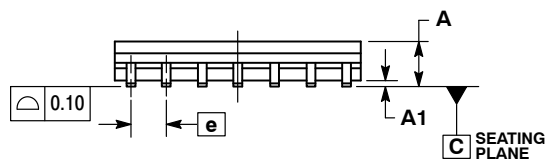
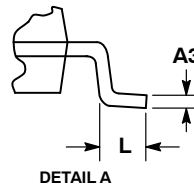
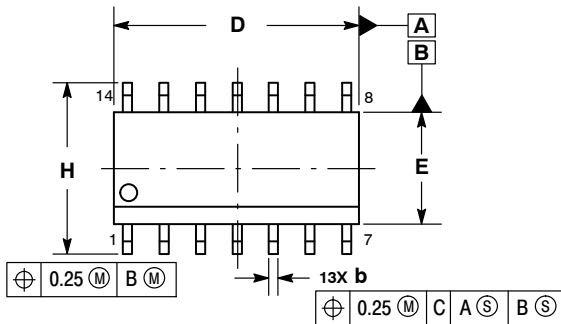
\*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable



SCALE 1:1

SOIC-14 NB  
CASE 751A-03  
ISSUE L

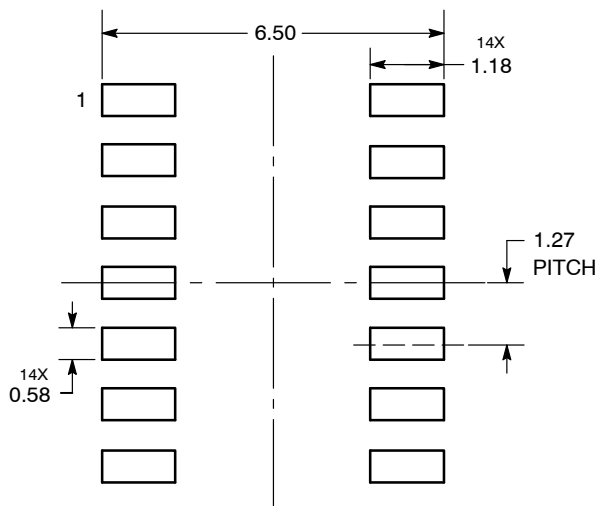
DATE 03 FEB 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
  5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

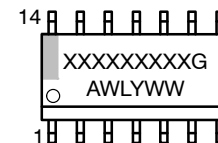
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42565B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-14 NB	PAGE 1 OF 2

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**SOIC-14**  
**CASE 751A-03**  
**ISSUE L**

DATE 03 FEB 2016

STYLE 1:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. NO CONNECTION  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 2:  
 CANCELLED

STYLE 3:  
 PIN 1. NO CONNECTION  
 2. ANODE  
 3. ANODE  
 4. NO CONNECTION  
 5. ANODE  
 6. NO CONNECTION  
 7. ANODE  
 8. ANODE  
 9. ANODE  
 10. NO CONNECTION  
 11. ANODE  
 12. ANODE  
 13. NO CONNECTION  
 14. COMMON CATHODE

STYLE 4:  
 PIN 1. NO CONNECTION  
 2. CATHODE  
 3. CATHODE  
 4. NO CONNECTION  
 5. CATHODE  
 6. NO CONNECTION  
 7. CATHODE  
 8. CATHODE  
 9. CATHODE  
 10. NO CONNECTION  
 11. CATHODE  
 12. CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 5:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. COMMON ANODE  
 8. COMMON CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 6:  
 PIN 1. CATHODE  
 2. CATHODE  
 3. CATHODE  
 4. CATHODE  
 5. CATHODE  
 6. CATHODE  
 7. CATHODE  
 8. ANODE  
 9. ANODE  
 10. ANODE  
 11. ANODE  
 12. ANODE  
 13. ANODE  
 14. ANODE

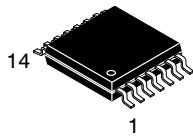
STYLE 7:  
 PIN 1. ANODE/CATHODE  
 2. COMMON ANODE  
 3. COMMON CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. COMMON CATHODE  
 12. COMMON ANODE  
 13. ANODE/CATHODE  
 14. ANODE/CATHODE

STYLE 8:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. COMMON ANODE  
 8. COMMON ANODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. NO CONNECTION  
 12. ANODE/CATHODE  
 13. ANODE/CATHODE  
 14. COMMON CATHODE

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**TSSOP-14 WB**  
CASE 948G  
ISSUE C

DATE 17 FEB 2016

SCALE 2:1



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**GENERIC MARKING DIAGRAM\***

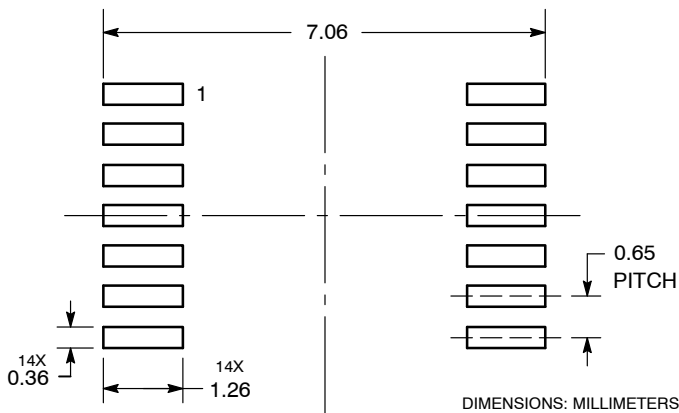


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

**SOLDERING FOOTPRINT**



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